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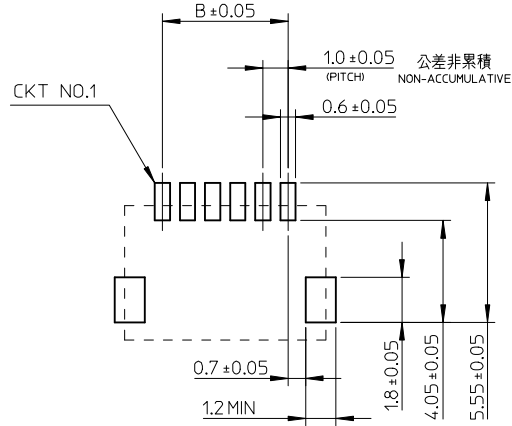
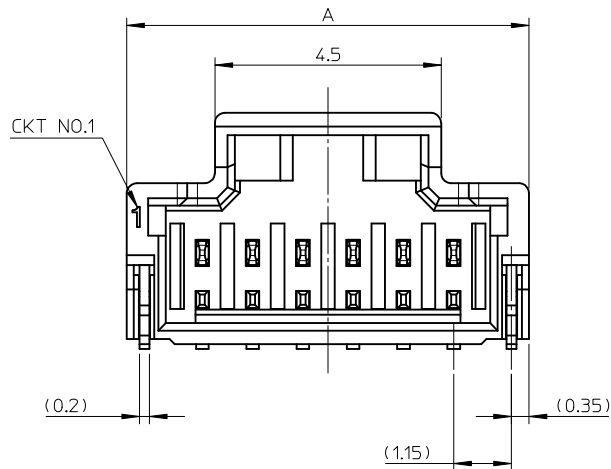
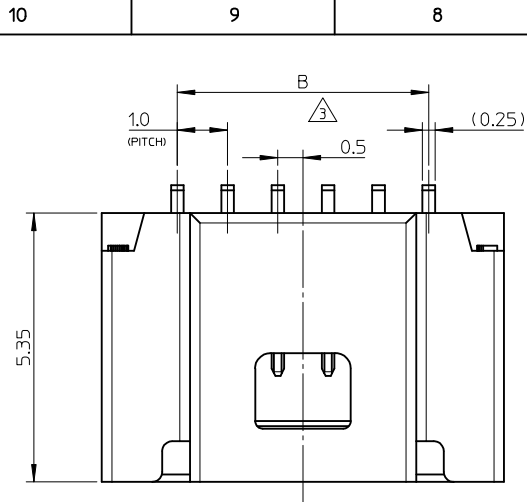
E

D

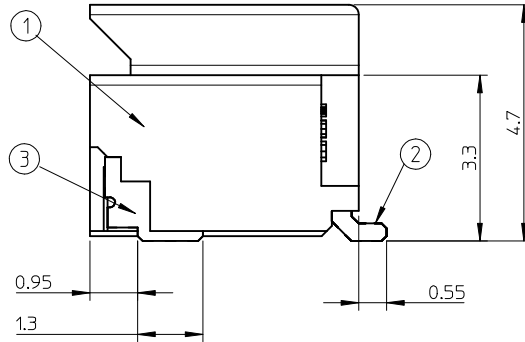
C

B

A



参考パターンレイアウト
RECOMMENDED PATTERN DIM.(REF)
SCALE:5-1



番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	耐熱ナイロン、UL94V-0 HEAT RESISTANCE NYLON, UL94V-0
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING
③	ネイル NAIL	黄銅 BRASS すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING

14.0	17.0	15
13.0	16.0	14
12.0	15.0	13
11.0	14.0	12
10.0	13.0	11
9.0	12.0	10
8.0	11.0	9
7.0	10.0	8
6.0	9.0	7
5.0	8.0	6
B	A	極数 CIRCUITS

NOTES

- かん相手 : 501330-****
MATE WITH : 501330-****
- ソルダーピン及びネイルの平坦度は0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- 極数 = 偶数に適用
APPLY FOR CKT SIZE=EVEN
- 2~5極は、SD-501568-001を参照下さい。
REFER TO SD-501568-001 ABOUT 2-5CKT.
- ELV AND RoHS COMPLIANT.

CONNECTOR SERIES No. 501568-***9

REVISED EC NO: J2010-0339 DRWN: INAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY AMIZUMURA	DATE 2005/01/19	TITLE 1.0 WIRE TO BOARD CONN. 1-ROW R/A WAFER ASSY 6-15CKT			
		10 OVER 30 UNDER	± 0.25	CHECKED BY MYAGI	DATE 2005/01/19				
		30 OVER	± 0.3	APPROVED BY ANODA	DATE 2005/01/19				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 2		SD-501568-002		1 OF 2		
REV		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

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10 9 8 7 6 5 4 3 2 1

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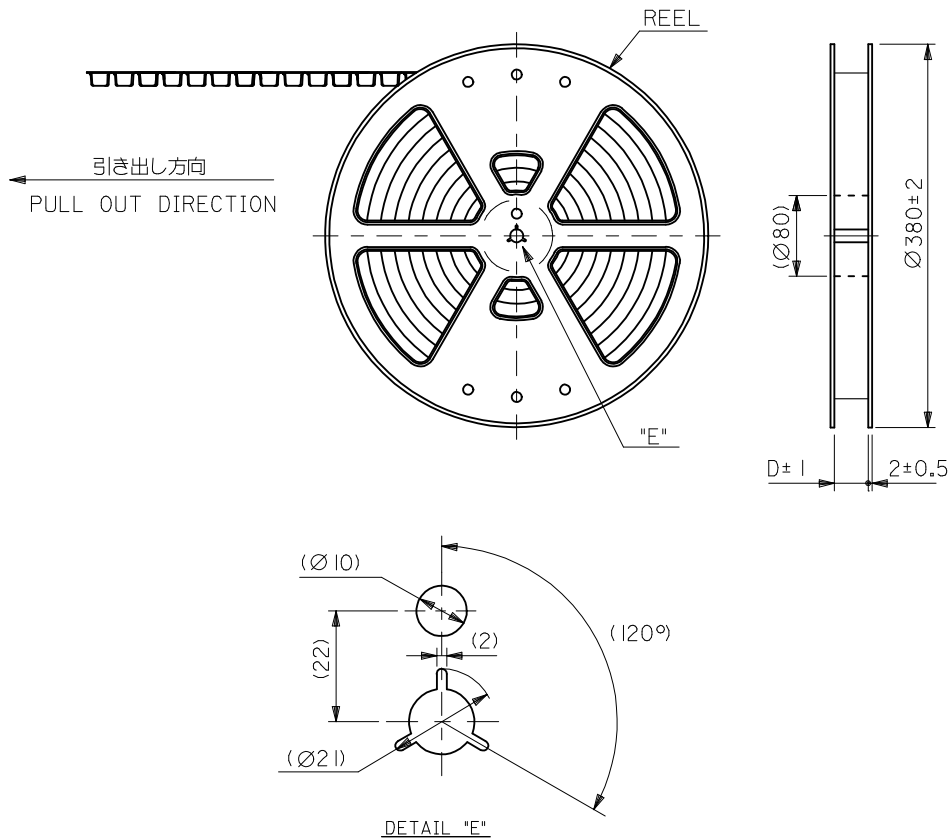
E

D

C

B

A



NOTES

- 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
- 梱包数量: 1300 個/リール
NUMBER OF CONNECTORS: 1300 PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH
トップテープ接着部(空エンボス)
20 PIECES. MIN.
TOP TAPE BONDED PART (EMPTY)
部品挿入部
COMPONENT SUPPLIER
末端部(空部)
TAIL PART (EMPTY)
160 MIN.
400 MIN.
- 材料
MATERIAL
キャリアテープ: ポリプロピレン
CARRIER TAPE: POLYPROPYLENE
トップテープ: PET, PE, REF
TOP TAPE
リール: ポリスチレン <リサイクル材を含む>
REEL: POLYSTYRENE <RECYCLE MATERIAL CONTAINED>
- ELV AND RoHS COMPLIANT.
- ハイバリア梱包(シリカゲル入り)対応品である。(501568-**-07除く)
THIS PRODUCT IS HIGH BARRIER PACKAGE (WITH SILICAGEL) (BESIDES 501568-**-07)
- 開梱後の保管条件に注意のこと。(ハイバリア品対象: PS-501568-001参照)
REFER TO PS-501568-001 (HIGH BARRIER PRODUCT) FOR CONDITIONS AFTER OPEN.

引き出し方向
PULL OUT DIRECTION

トップテープ接着部(空エンボス)
20 PIECES. MIN.
TOP TAPE BONDED PART (EMPTY)

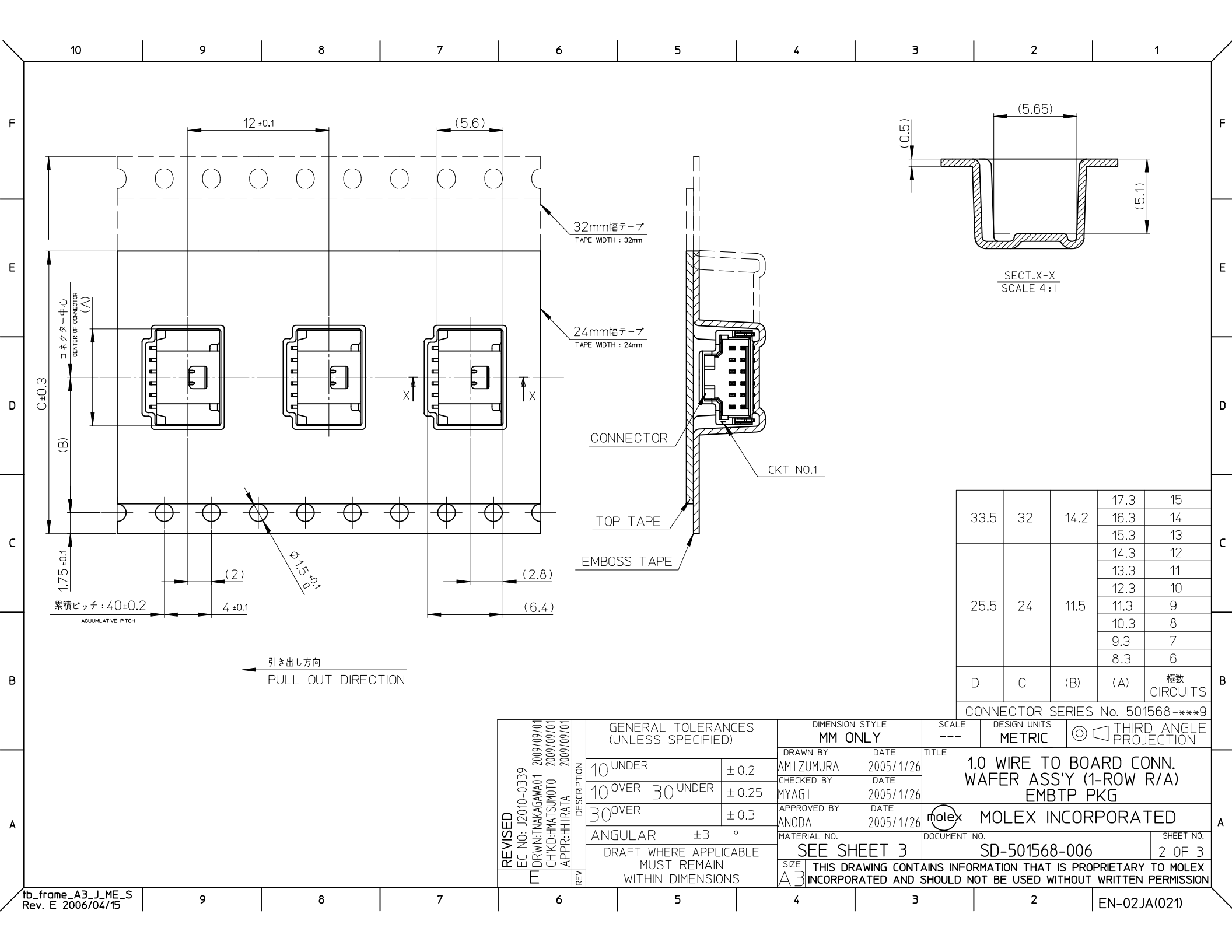
部品挿入部
COMPONENT SUPPLIER
末端部(空部)
TAIL PART (EMPTY)
160 MIN.

- 材料
MATERIAL
キャリアテープ: ポリプロピレン
CARRIER TAPE: POLYPROPYLENE
トップテープ: PET, PE, REF
TOP TAPE
リール: ポリスチレン <リサイクル材を含む>
REEL: POLYSTYRENE <RECYCLE MATERIAL CONTAINED>

5. ELV AND RoHS COMPLIANT.

- ハイバリア梱包(シリカゲル入り)対応品である。(501568-**-07除く)
THIS PRODUCT IS HIGH BARRIER PACKAGE (WITH SILICAGEL) (BESIDES 501568-**-07)
- 開梱後の保管条件に注意のこと。(ハイバリア品対象: PS-501568-001参照)
REFER TO PS-501568-001 (HIGH BARRIER PRODUCT) FOR CONDITIONS AFTER OPEN.

REVISED EC NO: J2010-0339 DRWN: TNAKAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY AMIZUMURA	DATE 2005/1/26	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTP PKG				
		10 OVER 30 UNDER	± 0.25	CHECKED BY MYAGI	DATE 2005/1/26					
		30 OVER	± 0.3	APPROVED BY ANODA	DATE 2005/1/26	MOLEX MOLEX INCORPORATED				
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.				SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 3		SD-501568-006				1 OF 3
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
	REV									



33.5	32	14.2	17.3	15
			16.3	14
			15.3	13
			14.3	12
			13.3	11
			12.3	10
25.5	24	11.5	11.3	9
			10.3	8
			9.3	7
			8.3	6
D	C	(B)	(A)	極数 CIRCUITS

CONNECTOR SERIES No. 501568-***9

REVISED EC NO: J2010-0339 DRWN: TNAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
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		30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/1/26	MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 3		SD-501568-006		2 OF 3		
	REV			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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